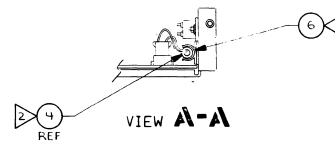
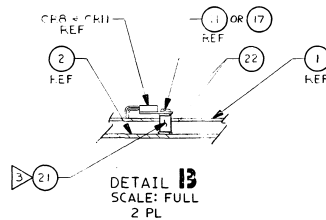
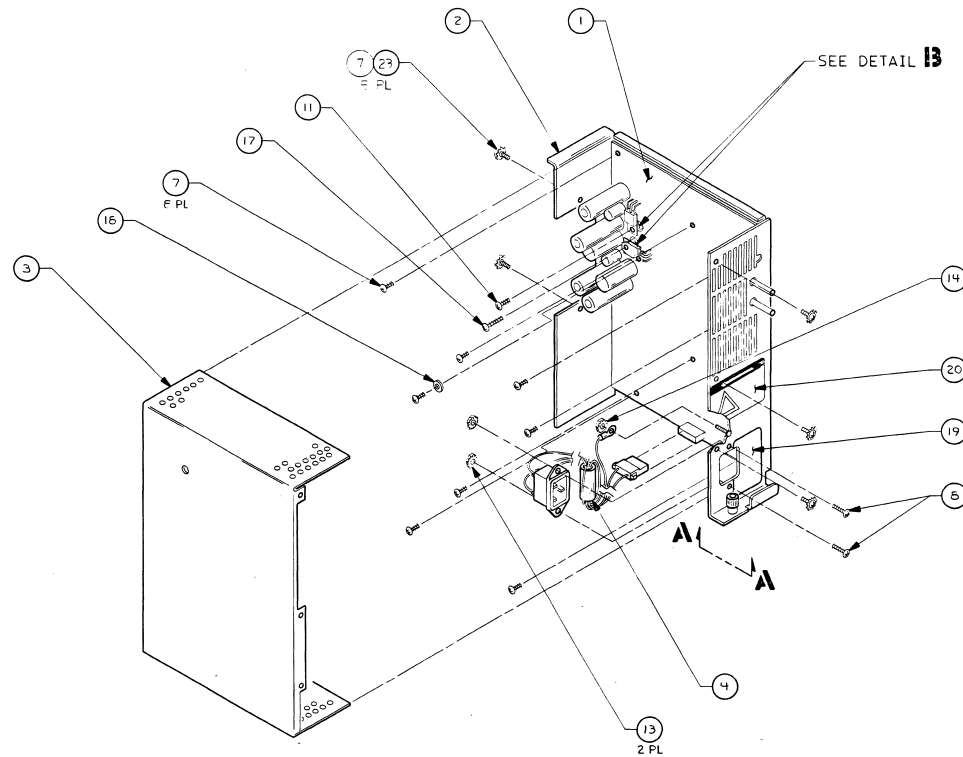


NOTE: UNLESS OTHERWISE SPECIFIED

- 1. REMOVE PAPER BACKING OF CABLE CLIP (ITEM 4), POSITION UNDER POWER RECEPTACLE.
- 2. PLACE CHIPS IN CLIP (ITEM 4) AFTER APPLYING A DROP OF RTV (ITEM 15) ON INSULATING CLIP SURFACE.
- 3. SLIP HEATING STANDOFF (ITEM 21) OVER CHASSIS STANDOFF, AND SOLDER CHASSIS (ITEM 22).



REV	ZONE	ECO	REVISION	APPRO
B			B281 REWORK IDENTIFICATION ONLY	
F			B287 REWORK IDENTIFICATION ONLY	
H			B198 REWORK IDENTIFICATION ONLY	
J			B295 REWORK IDENTIFICATION ONLY	
K			B313 REWORK IDENTIFICATION ONLY	
L			B324 REWORK IDENTIFICATION ONLY	

SEE SEPARATE BILL OF MATERIAL 620-5203

METRIC	apple computer inc.
1/2 X	POS
620-5203-L	1/1

620-5203-L 1/1